

ABSTRACT OF THE DISCLOSURE

The connection structure is obtained by electrically  
 connecting first electrodes on a first substrate 1 and  
 5 second electrodes on a second substrate with an interposed  
 anisotropic electroconductive adhesive layer 5 so as to  
 satisfy Eq. 1 below

$$0.5 \times \{(A^1 C^1 + A^2 C^2) / (B+C)\} \leq X \leq 2 \times \{(A^1 C^1 + A^2 C^2) / (B+C)\} \quad (1)$$

10 where  $A^1$  is the height of each first electrode,  $B^1$  is the  
 electrode width thereof,  $C^1$  is the width of the  
 interelectrode space,  $A^2$  is the height of each second  
 electrode,  $B^2$  is the electrode width thereof,  $C^2$  is the  
 15 width of the interelectrode space ( $B+C = B^1+C^1 = B^2+C^2$ ), and  
 X is the thickness of the electroconductive adhesive layer  
 prior to connection.